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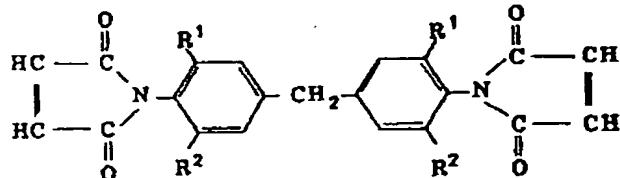
APPLICATION DATE : 11-08-89
APPLICATION NUMBER : 01206732

APPLICANT : MITSUBISHI PETROCHEM CO LTD;

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TITLE : EPOXY RESIN-BISMALEIMIDE
THERMOSETTING RESIN
COMPOSITION



ABSTRACT : PURPOSE: To provide the subject composition forming cured products having excellent heat resistance and low water absorbability and useful for multilayered laminate resins, sliding materials, sealing materials, molding materials, powder coatings, etc., by containing an epoxy compound, a bismaleimide and an alkenylphenol compound.

CONSTITUTION: The objective composition comprises (A) an epoxy compound having at least two epoxy groups in one molecule (e.g. bisphenol A diglycidyl ether), (B) a bismaleimide of the formula (R¹ is 1-4C alkyl; R² is H, methyl or ethyl) [e.g. N,N'-(3,3'-dimethyl-4,4'-diphenylmethane)bismaleimide] and (C) an alkenylphenol compound having at least two alkenyl groups in one molecule preferably in an A/B component weight ratio of 0.1-10 and a (A+B)/C component weight ratio of 0.5-20.

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